

ABSTRACT

A semiconductor package comprises a board, a plurality of solder bump pads, a plurality of board pads, a plurality of distribution patterns, a plurality of contact pads, at least one chip, a plurality of bonding wire, an encapsulation part and a plurality of solder bumps. In order to reduce the height of the loop of the bonding wires for connecting the bonding pad on the semiconductor chip to the board pads on the board, the ends of the bonding wires are connected to the bonding pads and board pads respectively by wedge bonding. Thus, a very thin package can be obtained. In addition, a thin package stack can be obtained by stacking the very thin packages.